12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20170314001
Transfer of select devices from ANAM-1 to FFAB Wafer Fab site
Change Notification / Sample Request

Date: March 30, 2017
To: TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The proposed first ship date is indicated on page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

20170314001
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TCA6507PWR	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20170314001	**PCN Date:**	Mar 30, 2017
Title:	Transfer of select devices from ANAM-1 to FFAB Wafer Fab site		
Customer Contact:	PCN Manager	**Dept:**	Quality Services
Proposed 1st Ship Date:	Jun 30, 2017	**Estimated Sample Availability:**	Date provided at sample request.

Change Type:

☐	Assembly Site	☐	Assembly Process	☐	Assembly Materials
☐	Design	☐	Electrical Specification	☐	Mechanical Specification
☐	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☒	Wafer Fab Site	☐	Wafer Fab Materials	☐	Wafer Fab Process
		☐	Part number change		

PCN Details

Description of Change:

This change notification is to announce the transfer of select devices from ANAM-1 to the FFAB Wafer Fab site. Fab support from ANAM-1 has been discontinued. Buffer inventory has been built to cover the notification period of this change notification.

Current (Discontinued)			New (Transfer to Location)		
Current Fab Site	**Process**	**Wafer Diameter**	**New Fab Site**	**Process**	**Wafer Diameter**
ANAM-1	LBC7	200mm	FFAB	LBC7	200mm

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

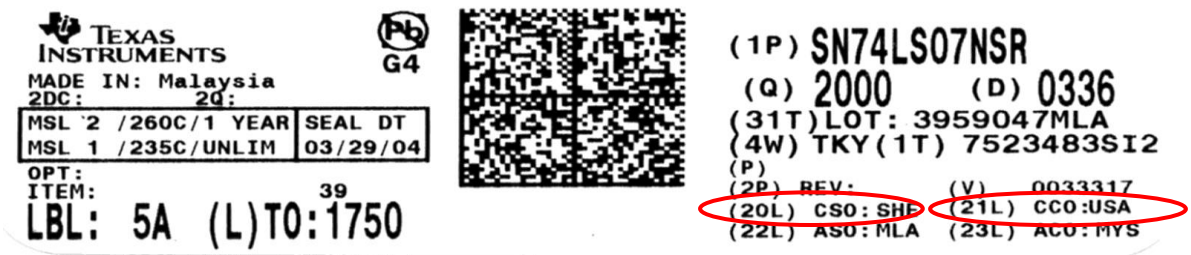
Current:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
ANAM-1	ANM	KOR	Bucheon-si

New Fab Site:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
FR-BIP-1	**TID**	**DEU**	**Freising**

Sample product shipping label (not actual product label)



Product Affected:

TCA6507PW	TCA6507PWR	TCA6507PWT	TCA6507ZXUR
TCA6507PWG4	TCA6507PWRG4	TCA6507RUER	

Qualification Report

TCA6507RUER (Transfer Dongbu FAB to FFAB)

Approve Date 03-Mar-2017

Product Attributes

Attributes	Qual Device: TCA6507RUER	QBS Product Reference: TCA6507RUER	QBS Process Reference: TCA6416PW	QBS Package Reference: TCA6507RUE
Assembly Site	NSE	NSE	MLA	NSE
Package Family	X2QFN	-	TSSOP	-
Wafer Fab Supplier	FFAB	FFAB	FFAB	ANAM
Wafer Process	LBC7	LBC7	LBC7	3370A07S

- QBS: Qual by Similarity
- Qual Device TCA6507RUER is qualified at LEVEL1-260C0G

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TCA6507RUER	QBS Product Reference: TCA6507RUER	QBS Process Reference: TCA6416PW	QBS Package Reference: TCA6507RUE
AC	Autoclave 121C	96 Hours	-	-	3/231/0	-
ED	Electrical Characterization	Per Datasheet Parameters	1/30/0	1/30/0	3/90/0	-
ELFR	Early Life Failure Rate, 125C	48 Hours	-	3/3000/0	-	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	3/231/0	3/231/0	-
HBM	ESD - HBM	2500 V	-	3/21/0	1/3/0	-
CDM	ESD - CDM	1000 V	-	3/21/0	-	-
HTOL	Life Test, 125C	1000 Hours	-	3/231/0	-	-
HTOL	Life Test, 150C	300 Hours	-	-	3/231/0	-
HTSL	High Temp. Storage Bake, 150C	1000 Hours	-	3/165/0	3/231/0	-
LU	Latch-up	(per JESD78)	-	3/30/0	1/9/0	-
PD	Physical Dimensions	--	-	3/60/0	-	3/15/0
SD	Surface Mount Solderability	Pb Free	-	3/15/0	-	-
TC	Temperature Cycle, -65/150C	500 Cycles	-	3/231/0	3/231/0	-
UHAST	Unbiased HAST, 130C/85%RH	96 Hours	-	3/231/0	-	-
WBP	Bond Pull	Wires	-	3/15/0	-	3/228/0
WBS	Ball Bond Shear	Wires	-	3/15/0	-	3/228/0

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free (SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com